


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CDO7*UY16CFY	A	BO2A	2017-04-12
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.9x3.9x1.75	8	gull wing	
Comment	Package: 07 SO 08 .15 JEDEC; MDF valid for TSX393IYDT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CDO7*UY16CFY				6000000.0	1000005.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.847	mg	supplier	die	Silicon (Si)	7440-21-3		0.822	mg	970484	10275
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	2361	25
				supplier	Passivation	Silicon Oxide	7631-86-9		0.014	mg	16529	175
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.009	mg	10626	113
Leadframe	Copper & its alloys	30.328	mg	supplier	alloy	Copper (Cu)	7440-50-8		30.072	mg	991559	375900
				supplier	alloy	Iron (Fe)	7439-89-6		0.015	mg	495	188
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.024	mg	791	300
				supplier	metallization	Silver (Ag)	7440-22-4		0.217	mg	7155	2713
Die attach	Other Organic Materials	0.338	mg	supplier	glue	Silver (Ag)	7440-22-4		0.297	mg	878698	3713
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.017	mg	50296	213
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.017	mg	50296	213
				supplier	glue	Acrylate polymer	87320-05-6		0.007	mg	20710	88
Bonding wires	Other inorganic materials	0.065	mg	supplier	wire	Copper (Cu)	7440-50-8		0.065	mg	1000000	813
Encapsulation	Other Organic Materials	47.364	mg	supplier	mold compound	Silica, vitreous	60676-86-0		41.017	mg	865995	512713
				supplier	mold compound	Epoxy Resin	25068-38-6		3.552	mg	74994	44400
				supplier	mold compound	Phenol Resin	29690-82-2		2.368	mg	49996	29600
				supplier	mold compound	Carbon black	1333-86-4		0.237	mg	5004	2963
				supplier	mold compound	Bismuth compound	7440-69-9		0.190	mg	4011	2375
connections coating	Solder	1.058	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.058	mg	1000000	13225